

10.70-11.70GHz 4-Watt Internally-Matched Power FET

FEATURES

- 10.70 -11.70GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.0 dBm Output Power at 1dB Compression
- 6.5 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -46 dBc IM3 at Po = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (T_a = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 10.7-11.7GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	35.5	36.0		dBm
G _{1dB}	Gain at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ $f = 10.7-11.7 \text{GHz}$	5.5	6.5		dB
ΔG	Gain Flatness $f = 10.7-11.7GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ f = 10.7-11.7GHz		30		%
Id _{1dB}	Drain Current at 1dB Compression f = 10.7-11.7GHz		1100	1300	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10$ MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² $V_{DS} = 10$ V, $I_{DSQ} \approx 65\%$ IDSS $f = 11.70$ GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		2000	2500	mA
V _P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
lgf	Forward Gate Current	48mA	14.4mA	
lgr	Reverse Gate Current	-9.6mA	-2.4mA	
Pin	Input Power	35.5dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Storage Temperature	-65C to +175C	-65C to +175C	
Pt	Total Power Dissipation	25W	25W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

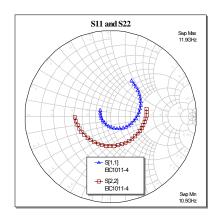
2. Exceeding any of the above ratings may reduce MTTF below design goals.

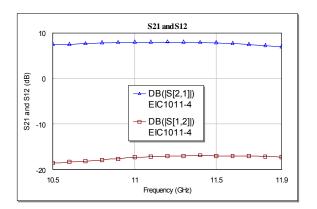


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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} = 1100mA



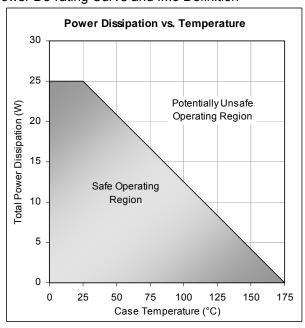


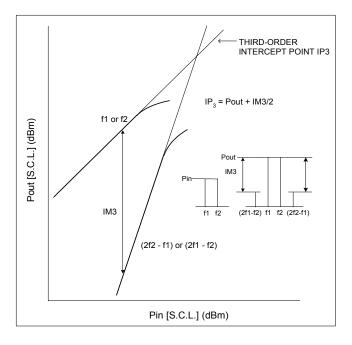
FREQ	S	11	S21		S12		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
10.0	0.5739	108.35	2.1901	-123.52	0.1038	-170.96	0.4584	55.24
10.2	0.5419	89.44	2.2517	-141.43	0.1081	171.77	0.4527	38.81
10.4	0.5027	69.8	2.3146	-159.96	0.1142	153.91	0.4397	21.79
10.6	0.454	49.43	2.3701	-178.6	0.1209	135.5	0.4186	2.16
10.8	0.3919	26.75	2.4477	162.08	0.1272	116.3	0.3848	-20.15
11.0	0.3168	2.48	2.5075	141.24	0.1368	95.69	0.359	-45.27
11.2	0.2355	-25.9	2.5133	119.63	0.1399	74.8	0.342	-75.08
11.4	0.1589	-62.62	2.4807	97.75	0.1436	52.35	0.3447	-107.19
11.6	0.1084	-118.22	2.4142	76.04	0.141	30.62	0.3633	-137.98
11.8	0.1171	176.36	2.2904	53.87	0.1378	9.3	0.4005	-166.15
12.0	0.1688	130.2	2.157	32.3	0.1337	-13.09	0.4409	169.07



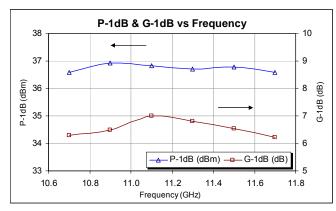
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Power De-rating Curve and IM3 Definition

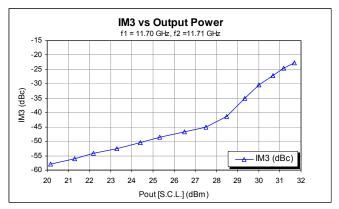




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 1100 mA)



Typical IM3 Data (V_{DS} = 10 V, I_{DSQ} ≈ 65% IDSS)



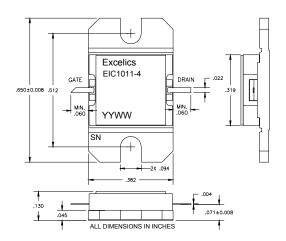


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PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

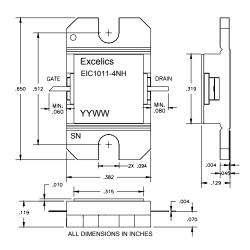
EIC1011-4 (Hermetic)





Caution! ESD sensitive device.

EIC1011-4NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²	
EIC1011-4	Hermetic	Industrial	10.70-11.70GHz	35.5	-43	
EIC1011-4NH	Non-Hermetic	Industrial	10.70-11.70GHz	35.5	-43	

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness